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August 2011

FSQ0365, FSQ0265, FSQ0165, FSQ321 Green Mode Fairchild Power Switch (FPS™) for Valley Switching Converter – Low EMI and High Efficiency

Features

- Optimized for Valley Switching Converter (VSC)
- Low EMI through Variable Frequency Control and Inherent Frequency Modulation
- High Efficiency through Minimum Voltage Switching
- Narrow Frequency Variation Range Over Wide Load and Input Voltage Variation
- Advanced Burst-Mode Operation for Low Standby Power Consumption
- Pulse-by-Pulse Current Limit
- Protection Functions: Overload Protection (OLP), Over-Voltage Protection (OVP), Abnormal Over-Current Protection (AOCP), Internal Thermal Shutdown (TSD)
- Under-Voltage Lockout (UVLO) with Hysteresis
- Internal Startup Circuit
- Internal High-Voltage SenseFET: 650V
- Built-in Soft-Start: 15ms

Applications

- Power Supplies for DVP Player, DVD Recorder, Set-Top Box
- Adapter
- Auxiliary Power Supply for PC, LCD TV, and PDP TV

Description

A Valley Switching Converter generally shows lower EMI and higher power conversion efficiency than a conventional hard-switched converter with a fixed switching frequency. The FSQ-series is an integrated Pulse-Width Modulation (PWM) controller and SenseFET specifically designed for valley switching operation with minimal external components. The PWM controller includes an integrated fixed-frequency oscillator, under-voltage lockout, Leading-Edge Blanking (LEB), optimized gate driver, internal soft-start, temperature-compensated precise current sources for loop compensation, and self-protection circuitry.

Compared with discrete MOSFET and PWM controller solutions, the FSQ-series reduces total cost, component count, size and weight; while simultaneously increasing efficiency, productivity, and system reliability. This device provides a basic platform for cost-effective designs of valley switching fly-back converters.

Related Application Notes

- AN-4137 Design Guidelines for Offline Flyback Converters Using Fairchild Power Switch (FPSTM)
- AN-4141 Troubleshooting and Design Tips for <u>Fairchild Power Switch (FPS™) Flyback</u> Applications
- AN-4147 Design Guidelines for RCD Snubber of Flyback Converters
- AN-4150 Design Guidelines for Flyback Converters Using FSQ-series Fairchild Power Switch (FPS™)
- AN-4134 Design Guidelines for Off-line Forward Converters Using Fairchild Power Switch (FPS™)

Ordering Information

				Maximum Output Table ⁽¹⁾						
Part Number	Package		Current R		230V _{AC} ±15% ⁽²⁾		85-265V _{AC}		Replaces	
	. donago	Temperature	Limit	(Max.)	Adapter ⁽³⁾	Open Frame ⁽⁴⁾	Adapter ⁽³⁾	Open Frame ⁽⁴⁾	Devices	
FSQ321	8-DIP									
FSQ321L	8-LSOP					12W			FSDL321	
FSQ321LX	8-LSOP (Tape & Reel)	-40 to +85°C	0.6A 19	19Ω	8W		7W	10W	FSDM311	
FSQ0165RN	8-DIP			0.9Α 10Ω						
FSQ0165RL	8-LSOP		0.9A 1							
FSQ0165RLX	8-LSOP (Tape & Reel)	-40 to +85°C			0Ω 10W	15W	9W	13W	FSDL0165RN	
FSQ0265RN	8-DIP	40 to 195°C	1 2 4		14W	20W	11\/	16W	FSDM0265RN	
FSQ0265RL	8-LSOP	-40 to +85°C	1.2A	6Ω	1444	2000	11W		FSDM0265RNB	
FSQ0365RN	8-DIP	40 to 195°C	1 5 4	1.5A 4.5Ω	47.5\4	25\//	12\\	19W	FSDM0365RN	
FSQ0365RL	8-LSOP	-40 to +85°C	, 1.5A		17.5W	25W 13W	13W		FSDM0365RNB	

- The junction temperature can limit the maximum output power.
- $230\dot{V}_{AC}$ or $100/115V_{AC}$ with voltage doubler. The maximum power with CCM operation
- Typical continuous power in a non-ventilated, enclosed adapter measured at 50°C ambient temperature. Maximum practical continuous power in an open-frame design at 50°C ambient temperature.

Application Circuit

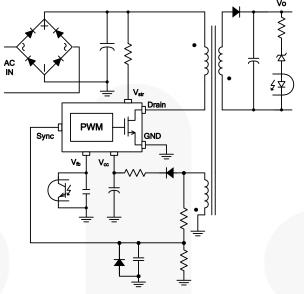


Figure 1. Typical Flyback Application

Internal Block Diagram

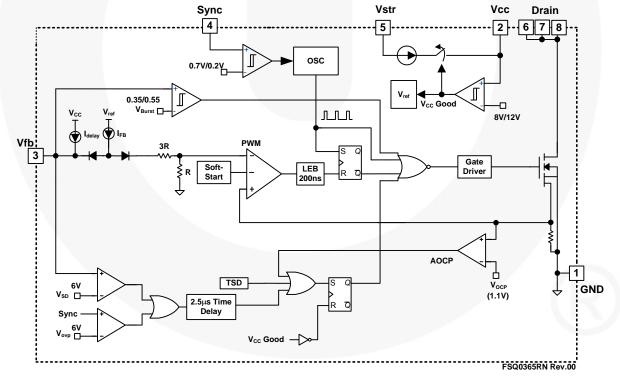


Figure 2. Internal Block Diagram

Pin Assignments

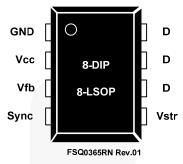


Figure 3. Pin Configuration (Top View)

Pin Definitions

Pin#	Name	Description
1	GND	SenseFET source terminal on primary side and internal control ground.
2	V _{CC}	Positive supply voltage input. Although connected to an auxiliary transformer winding, current is supplied from pin 5 (Vstr) via an internal switch during startup (see Figure 2). It is not until V _{CC} reaches the UVLO upper threshold (12V) that the internal startup switch opens and device power is supplied via the auxiliary transformer winding.
3	Vfb	The feedback voltage pin is the non-inverting input to the PWM comparator. It has a 0.9mA current source connected internally while a capacitor and opto-coupler are typically connected externally. There is a time delay while charging external capacitor C_{fb} from 3V to 6V using an internal $5\mu A$ current source. This delay prevents false triggering under transient conditions, but still allows the protection mechanism to operate under true overload conditions.
4	Sync	This pin is internally connected to the sync-detect comparator for valley switching. Typically the voltage of the auxiliary winding is used as Sync input voltage and external resistors and capacitor are needed to make delay to match valley point. The threshold of the internal sync comparator is 0.7V/0.2V.
5	Vstr	This pin is connected to the rectified AC line voltage source. At startup, the internal switch supplies internal bias and charges an external storage capacitor placed between the Vcc pin and ground. Once the V_{CC} reaches 12V, the internal switch is opened.
6, 7, 8	Drain	The drain pins are designed to connect directly to the primary lead of the transformer and are capable of switching a maximum of 650V. Minimizing the length of the trace connecting these pins to the transformer decreases leakage inductance.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A=25^{\circ}C$, unless otherwise specified.

Symbol	Parameter		Min.	Max.	Unit
V _{STR}	Vstr Pin Voltage		500		V
V _{DS}	Drain Pin Voltage		650		V
V _{CC}	Supply Voltage		20	V	
V _{FB}	Feedback Voltage Range		-0.3	9.0	V
V _{Sync}	Sync Pin Voltage		-0.3	9.0	V
		FSQ0365		12.0	
	Drain Current Pulsed ⁽⁶⁾	FSQ0265		8.0	Δ.
I _{DM}		FSQ0165		4.0	Α
		FSQ321		1.5	
		FSQ0365		230	
_/	Single Pulsed Avalanche Energy ⁽⁷⁾	FSQ0265		140	mJ
E _{AS}		FSQ0165		50	
		FSQ321		10	
P _D	Total Power Dissipation			1.5	W
T_J	Recommended Operating Junction T	-40	Internally Limited	°C	
T _A	Operating Ambient Temperature	-40	+85	°C	
T _{STG}	Storage Temperature	-55	+150	°C	
ESD	Human Body Model; JESD22-A114	CLASS 1C			
EOD	Machine Model; JESD22-A115			CLASS B	

Notes:

- 5. Repetitive rating: Pulse width limited by maximum junction temperature.
- 6. L=51mH, starting T_J=25°C.

Thermal Impedance

Symbol	Symbol Parameter		Unit
8-DIP ⁽⁷⁾		У	
θ_{JA}	Junction-to-Ambient Thermal Resistance ⁽⁸⁾	80	
θ_{JC}	Junction-to-Case Thermal Resistance ⁽⁹⁾	20	°C/W
θ_{JT}	Junction-to-Top Thermal Resistance ⁽¹⁰⁾	35	

Notes:

- All items are tested with the standards JESD 51-2 and 51-10 (DIP).
- 8. Free-standing with no heat-sink, under natural convection.
- 9. Infinite cooling condition refer to the SEMI G30-88.
- 10. Measured on the package top surface.

Electrical Characteristics

 $T_A \text{=} 25^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter		Condition	Min.	Тур.	Max.	Unit
SenseFET :	Section						
BV_{DSS}	Drain-Source Breakd	own Voltage	V_{CC} =0V, I_D =100 μ A	650			V
I _{DSS}	Zero-Gate-Voltage D	rain Current	V _{DS} =650V			100	μΑ
		FSQ0365			3.5	4.5	
D	Drain-Source On-	FSQ0265	T _J =25°C, I _D =0.5A		5.0	6.0	0
$R_{DS(ON)}$	State Resistance ⁽¹¹⁾	FSQ0165	1 J-25 C, ID-0.5A		8.0	10.0	Ω
		FSQ321			14.0	19.0	
		FSQ0365			315		
C	Innut Canacitanas	FSQ0265	\/ -0\/ \/ -25\/ f-1MHz		550		nΕ
C_{ISS}	Input Capacitance	FSQ0165	V_{GS} =0V, V_{DS} =25V, f=1MHz		250		pF
		FSQ321			162		
		FSQ0365		\	47		
0	0	FSQ0265)/ 0)/)/ 05\/ 6 4\M\ -		38		pF
Coss	Output Capacitance	FSQ0165	V_{GS} =0V, V_{DS} =25V, f=1MHz		25		
		FSQ321			18		
		FSQ0365	V =0V V =25V f=4MU=		9.0		pF
0	Reverse Transfer Capacitance	FSQ0265			17.0		
C_{RSS}		FSQ0165	V_{GS} =0V, V_{DS} =25V, f=1MHz		10.0		
		FSQ321			3.8		
	Turn-On Delay	FSQ0365			11.2		ns
		FSQ0265	- - - V _{DD} =350V, I _D =25mA		20.0		
$t_{d(on)}$		FSQ0165			12.0		
		FSQ321			9.5		
		FSQ0365	- - - - V _{DD} =350V, I _D =25mA		34		ns
		FSQ0265			15		
t _r	Rise Time	FSQ0165			4		
		FSQ321			19	/	
		FSQ0365			28.2		
	T 0"5 !	FSQ0265	.,		55.0		
$t_{d(off)}$	Turn-Off Delay	FSQ0165	$-V_{DD}$ =350V, I_{D} =25mA		30.0		ns
		FSQ321			33.0		
		FSQ0365			32		
	E. II T'	FSQ0265), osovi i os		25		
t _f	Fall Time	FSQ0165	V_{DD} =350V, I_{D} =25mA		10		ns
FSQ3		FSQ321			42		
Burst-Mode	Section		•	1			
V _{BURH}				0.45	0.55	0.65	V
V_{BURL}	Burst-Mode Voltage		T _J =25°C, t _{PD} =200ns ⁽¹²⁾	0.25	0.35	0.45	V
V _{BUR(HYS)}					200		mV

Continued on the following page...

Electrical Characteristics (Continued)

T_A=25°C unless otherwise specified.

Symbol	Parameter		Conditions	Min.	Тур.	Max.	Unit	
Control Sec	ction			-	-	•		
t _{ON.MAX1}	Maximum On Time1	All but FSQ321	T _J =25°C	10.5	12.0	13.5	μs	
t _{ON.MAX2}	Maximum On Time2	FSQ321	T _J =25°C	6.35	7.06	7.77	μs	
t _{B1}	Blanking Time1	All but FSQ321		13.2	15.0	16.8	μs	
t _{B2}	Blanking Time2	FSQ321		7.5	8.2		μs	
t _W	Detection Time Window		T _J =25°C, V _{sync} =0V		3.0		μs	
Δf_{S}	Switching Frequency Varia	ation ⁽¹⁴⁾	-25°C < T _J < 85°C		±5	±10	%	
I _{FB}	Feedback Source Current		V _{FB} =0V	700	900	1100	μA	
D _{MIN}	Minimum Duty Cycle		V _{FB} =0V			0	%	
V _{START}	LIVA O The section LIVA		AGGET	11	12	13	V	
V_{STOP}	UVLO Threshold Voltage		After Turn-on	7	8	9	V	
t _{S/S1}	Internal Soft-Start Time 1	All but FSQ321	With Free-Running Frequency		15		ms	
t _{S/S2}	Internal Soft-Start Time 2	FSQ321	With Free-Running Frequency		10		ms	
Protection	Section					I.		
	Peak Current Limit	FSQ0365	T _J =25°C, di/dt=240mA/µs	1.32	1.50	1.68		
		FSQ0265	T _J =25°C, di/dt=200mA/µs	1.06	1.20	1.34	A	
I _{LIM}		FSQ0165	T _J =25°C, di/dt=175mA/µs	0.8	0.9	1.0		
		FSQ321	T _J =25°C, di/dt=125mA/µs	0.53	0.60	0.67		
V _{SD}	Shutdown Feedback Volta		V _{CC} =15V	5.5	6.0	6.5	V	
I _{DELAY}	Shutdown Delay Current		V _{FB} =5V	4.0	5.0	6.0	μA	
t _{LEB}	Leading-Edge Blanking Ti	me ⁽¹³⁾			200		ns	
V _{OVP}	Over-Voltage Protection		V _{CC} =15V, V _{FB} =2V	5.5	6.0	6.5	V	
t _{OVP}	Over-Voltage Protection E	lanking		2	3	4	μs	
T _{SD}	Thermal Shutdown Tempe	erature ⁽¹³⁾		125	140	155	°C	
Sync Section						, , , , , , , , , , , , , , , , , , ,		
V _{SH}				0.55	0.70	0.85	V	
V _{SL}	Sync Threshold Voltage			0.14	0.20	0.26	V	
t _{Sync}	Sync Delay Time ^(13,14)				300		ns	
Total Devic								
I _{OP}	Operating Supply Current (Control Part Only)		V _{CC} =15V	1	3	5	mA	
I _{START}	Start Current		V _{CC} =V _{START} - 0.1V (Before V _{CC} Reaches V _{START})	270	360	450	μΑ	
I _{CH}	Startup Charging Current		V _{CC} =0V, V _{STR} =Minimum 40V	0.65	0.85	1.00	mA	
V _{STR}	Minimum V _{STR} Supply Vol	tage			26		V	

Notes:

- 11. Pulse test: Pulse-Width=300μs, duty=2%.
- 12. Propagation delay in the control IC.
- 13. Though guaranteed, it is not 100% tested in production.
- 14. Includes gate turn-on time.

Comparison Between FSDM0x65RNB and FSQ-Series

Function	FSDM0x65RNB	FSQ-Series	Advantages of FSQ-Series
Operation Method	Constant	Valley Switching	■ Improved efficiency by valley switching
	Frequency PWM	Operation	■ Reduced EMI noise
EMI Reduction	Frequency Modulation	Valley Switching & Inherent Frequency Modulation	■ Reduce EMI noise in two ways
Burst-Mode	Burst-Mode Advanced Burst-		Improved standby power by valley switching also in burst-mode
Operation	Fixed Burst Peak	Mode	 Because the current peak during burst operation is dependent on V_{FB}, it is easier to solve audible noise
Protection		AOCP	 Improved reliability through precise abnormal over- current protection

Typical Performance Characteristics

Characteristic graphs are normalized at T_A=25°C.

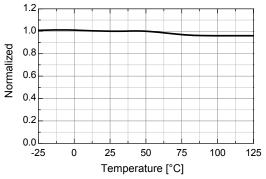


Figure 4.

Operating Supply Current (I_{OP}) vs. T_A

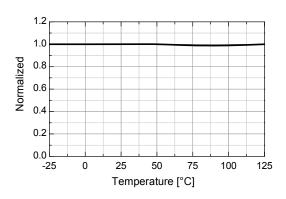


Figure 5. UVLO Start Threshold Voltage (V_{START})

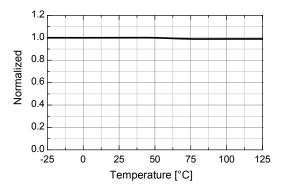


Figure 6. UVLO Stop Threshold Voltage (V_{STOP}) vs. T_A

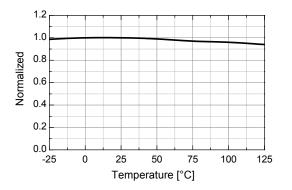


Figure 7. Startup Charging Current (I_{CH}) vs. T_A

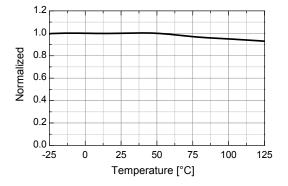


Figure 8. Initial Switching Frequency (f_S) vs. T_A

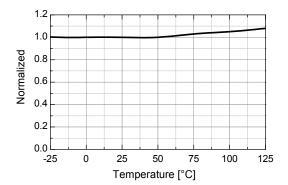


Figure 9. Maximum On Time (t_{ON.MAX}) vs. T_A

Typical Performance Characteristics (Continued)

Characteristic graphs are normalized at T_A=25°C.

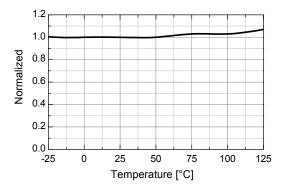


Figure 10. Blanking Time (t_B) vs. T_A

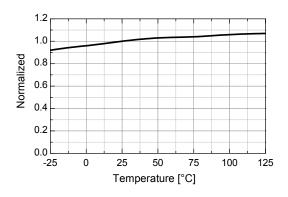


Figure 11. Feedback Source Current (IFB) vs. TA

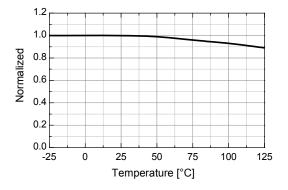


Figure 12. Shutdown Delay Current (I_{DELAY}) vs. T_A

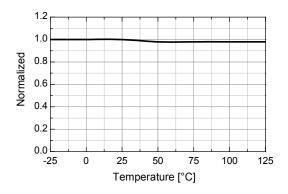


Figure 13. Burst Mode High Threshold Voltage (V_{burh}) vs. T_A

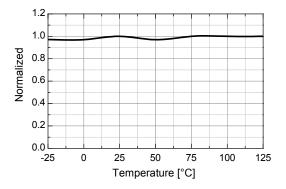


Figure 14. Burst Mode Low Threshold Voltage (V_{burl}) vs. T_A

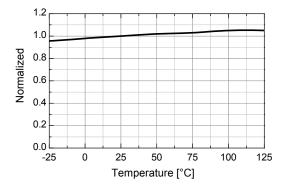
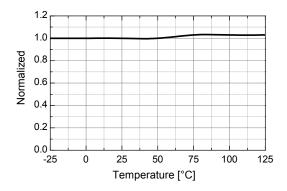


Figure 15. Peak Current Limit (I_{LIM}) vs. T_A

Typical Performance Characteristics (Continued)

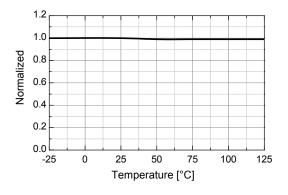
Characteristic graphs are normalized at T_A=25°C.



1.2 1.0 0.8 0.6 0.4 0.2 0.0 -25 0 25 50 75 100 125 Temperature [°C]

Figure 16. Sync High Threshold (V_{SH}) vs. T_A

Figure 17. Sync Low Threshold Voltage (V_{SL}) vs. T_A



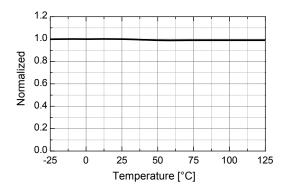


Figure 18. Shutdown Feedback Voltage (V_{SD}) vs. T_A

Figure 19. Over-Voltage Protection (V_{OP}) vs. T_A

Functional Description

1. Startup: At startup, an internal high-voltage current source supplies the internal bias and charges the external capacitor (C_a) connected to the V_{CC} pin, as illustrated in Figure 20. When V_{CC} reaches 12V, the FPSTM begins switching and the internal high-voltage current source is disabled. The FPS continues its normal switching operation and the power is supplied from the auxiliary transformer winding unless V_{CC} goes below the stop voltage of 8V.

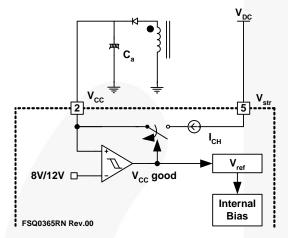


Figure 20. Startup Circuit

- 2. Feedback Control: FPS employs Current Mode control, as shown in Figure 21. An opto-coupler (such as FOD817A) and shunt regulator (such as KA431) are often used to implement the feedback network. Comparing the feedback voltage with the voltage across the R_{SENSE} resistor makes it possible to control the switching duty cycle. When the reference pin voltage of the shunt regulator exceeds the internal reference voltage of 2.5V, the opto-coupler LED current increases, pulling down the feedback voltage and reducing the duty cycle. This event typically occurs when input voltage is increased or output load is decreased.
- **2.1 Pulse-by-Pulse Current Limit**: Because Current Mode control is employed, the peak current through the SenseFET is limited by the inverting input of PWM comparator (V_{FB}^*), as shown in Figure 21. Assuming that the 0.9mA current source flows only through the internal resistor ($3R+R=2.8k\Omega$), the cathode voltage of diode D2 is about 2.5V. Since D1 is blocked when the feedback voltage (V_{FB}) exceeds 2.5V, the maximum voltage of the cathode of D2 is clamped at this voltage, clamping V_{FB}^* . Therefore, the peak value of the current through the SenseFET is limited.
- **2.2 Leading-Edge Blanking (LEB)**: At the instant the internal SenseFET is turned on, a high-current spike usually occurs through the SenseFET, caused by primary-side capacitance and secondary-side rectifier reverse recovery. Excessive voltage across the R_{sense} resistor would lead to incorrect feedback operation in the Current Mode PWM control. To counter this effect, the FPS employs a leading-edge blanking (LEB) circuit. This circuit inhibits the PWM comparator for a short time (t_{LEB}) after the SenseFET is turned on.

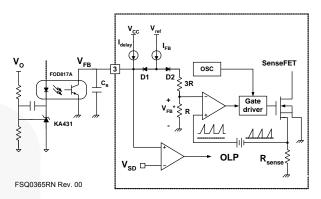


Figure 21. Pulse-Width-Modulation (PWM) Circuit

3. Synchronization: The FSQ-series employs a valley switching technique to minimize the switching noise and loss. The basic waveforms of the valley switching converter are shown in Figure 22. To minimize the MOSFET's switching loss, the MOSFET should be turned on when the drain voltage reaches its minimum value, as shown in Figure 22. The minimum drain voltage is indirectly detected by monitoring the $V_{\rm CC}$ winding voltage, as shown in Figure 22.

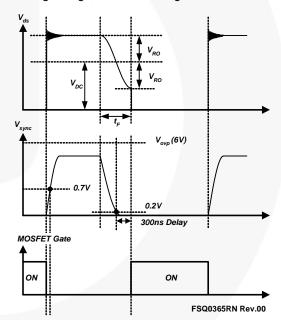


Figure 22. Valley Resonant Switching Waveforms

4. Protection Circuits: The FSQ-series has several self-protective functions, such as Overload Protection (OLP), Abnormal Over-Current protection (AOCP), Over-Voltage Protection (OVP), and Thermal Shutdown (TSD). All the protections are implemented as Auto-Restart Mode. Once the fault condition is detected, switching is terminated and the SenseFET remains off. This causes V_{CC} to fall. When V_{CC} falls down to the Under-Voltage Lockout (UVLO) stop voltage of 8V, the protection is reset and the startup circuit charges the V_{CC} capacitor. When the V_{CC} reaches the start voltage of 12V, the FSQ-series resumes normal operation. If the fault condition is not removed, the SenseFET remains off and V_{CC} drops to stop voltage again. In this manner,

the auto-restart can alternately enable and disable the switching of the power SenseFET until the fault condition is eliminated. Because these protection circuits are fully integrated into the IC without external components, the reliability is improved without increasing cost.

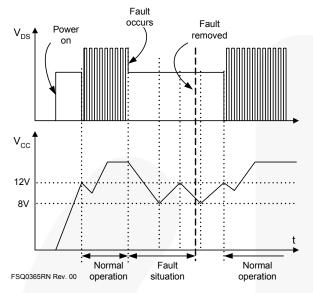


Figure 23. Auto-Restart Protection Waveforms

4.1 Overload Protection (OLP): Overload is defined as the load current exceeding its normal level due to an unexpected abnormal event. In this situation, the protection circuit should trigger to protect the SMPS. However, even when the SMPS is in the normal operation, the overload protection circuit can be triggered during load transition. To avoid this undesired operation, the overload protection circuit is designed to trigger only after a specified time to determine whether it is a transient situation or a true overload situation. Because of the pulse-by-pulse current limit capability, the maximum peak current through the SenseFET is limited, and therefore the maximum input power is restricted with a given input voltage. If the output consumes more than this maximum power, the output voltage (V_O) decreases below the set voltage. This reduces the current through the opto-coupler LED, which also reduces the opto-coupler transistor current, thus increasing the feedback voltage (V_{FB}) . If V_{FB} exceeds 2.8V, D1 is blocked and the 5µA current source starts to charge CB slowly up to V_{CC}. In this condition, V_{FB} continues increasing until it reaches 6V, when the switching operation is terminated, as shown in Figure 24. The delay for shutdown is the time required to charge CB from 2.8V to 6V with 5µA. A 20 ~ 50ms delay is typical for most applications.

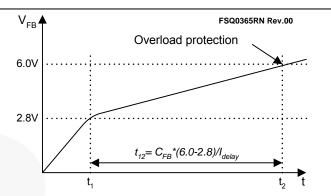


Figure 24. Overload Protection

4.2 Abnormal Over-Current Protection (AOCP): When the secondary rectifier diodes or the transformer pins are shorted, a steep current with extremely high-di/dt can flow through the SenseFET during the LEB time. Even though the FSQ-series has Overload Protection (OLP), it is not enough to protect the FSQ-series in that abnormal case, since severe current stress is imposed on the SenseFET until OLP triggers. The FSQ-series has an internal Abnormal Over-Current Protection (AOCP) circuit as shown in Figure 25. When the gate turn-on signal is applied to the power SenseFET, the AOCP block is enabled and monitors the current through the sensing resistor. The voltage across the resistor is compared with a preset AOCP level. If the sensing resistor voltage is greater than the AOCP level, the set signal is applied to the latch, resulting in the shutdown of the SMPS.

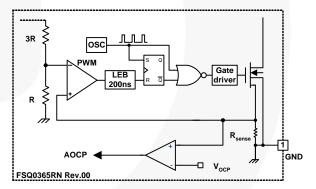


Figure 25. Abnormal Over-Current Protection

- 4.3 Over-Voltage Protection (OVP): If the secondaryside feedback circuit malfunctions or a solder defect causes an opening in the feedback path, the current through the opto-coupler transistor becomes almost zero. Then V_{FB} climbs up in a similar manner to the overload situation, forcing the preset maximum current to be supplied to the SMPS until the overload protection triggers. Because more energy than required is provided to the output, the output voltage may exceed the rated voltage before the overload protection triggers, resulting in the breakdown of the devices in the secondary side. To prevent this situation, an OVP circuit is employed. In general, the peak voltage of the sync signal is proportional to the output voltage and the FSQ-series uses a sync signal instead of directly monitoring the output voltage. If the sync signal exceeds 6V, an OVP is triggered, shutting down the SMPS. To avoid undesired triggering of OVP during normal operation, the peak voltage of the sync signal should be designed below 6V.
- **4.4 Thermal Shutdown (TSD)**: The SenseFET and the control IC are built in one package. This makes it easy for the control IC to detect the abnormal over temperature of the SenseFET. If the temperature exceeds ~150°C, the thermal shutdown triggers.
- **5. Soft-Start**: An internal soft-start circuit increases PWM comparator inverting input voltage with the SenseFET current slowly after it starts up. The typical soft-start time is 15ms. The pulsewidth to the power switching device is progressively increased to establish the correct working conditions for transformers, inductors, and capacitors. The voltage on the output capacitors is progressively increased with the intention of smoothly establishing the required output voltage. This helps prevent transformer saturation and reduces stress on the secondary diode during startup.
- **6. Burst Operation**: To minimize power dissipation in Standby Mode, the FPS enters Burst-Mode operation. As the load decreases, the feedback voltage decreases. As shown in Figure 26, the device automatically enters Burst Mode when the feedback voltage drops below V_{BURL} (350mV). At this point, switching stops and the output voltages start to drop at a rate dependent on standby current load. This causes the feedback voltage to rise. Once it passes V_{BURH} (550mV), switching resumes. The feedback voltage then falls and the process repeats. Burst Mode alternately enables and disables switching of the power SenseFET, reducing switching loss in Standby Mode.

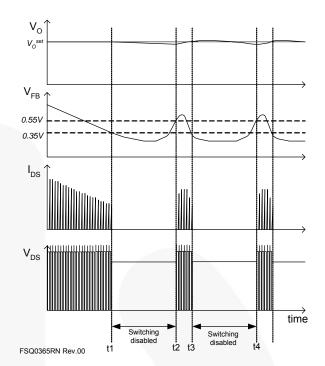


Figure 26. Waveforms of Burst Operation

7. Switching Frequency Limit: To minimize switching loss and Electromagnetic Interference (EMI), the MOSFET turns on when the drain voltage reaches its minimum value in valley switching operation. However, this causes switching frequency to increases at light load conditions. As the load decreases, the peak drain current diminishes and the switching frequency increases. This results in severe switching losses at light-load condition, as well as intermittent switching and audible noise. Because of these problems, the valley switching converter topology has limitations in a wide range of applications.

To overcome this problem, FSQ-series employs a frequency-limit function, as shown in Figure 27 and Figure 28. Once the SenseFET is turned on, the next turn-on is prohibited during the blanking time ($t_{\rm B}$). After the blanking time, the controller finds the valley within the detection time window ($t_{\rm W}$) and turns on the MOSFET, as shown in Figure 27 and Figure 28 (cases A, B, and C). If no valley is found during $t_{\rm W}$, the internal SenseFET is forced to turn on at the end of $t_{\rm W}$ (case D). Therefore, FSQ devices have a minimum switching frequency of 55kHz and a maximum switching frequency of 67kHz, as shown in Figure 28.

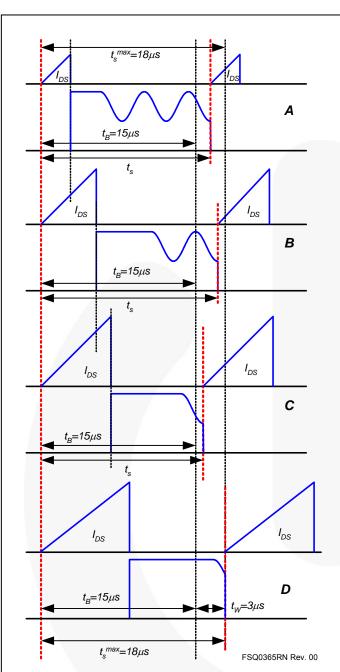


Figure 27. Valley Switching with Limited Frequency

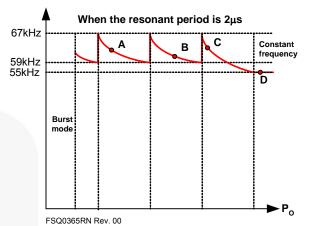


Figure 28. Switching Frequency Range

Typical Application Circuit of FSQ0365RN

Application	FPS Device	Input Voltage Range	Rated Output Power	Output Voltage (Maximum Current)
DVD Player	FSQ0365RN	85-265V _{AC}		5.1V (1.0A) 3.4V (1.0A)
Power Supply			19W	12V (0.4A)
				16V (0.3A)

Features

- High efficiency (>77% at universal input)
- Low standby mode power consumption (<1W at 230V_{AC} input and 0.5W load)
- Reduce EMI noise through Valley Switching operation
- Enhanced system reliability through various protection functions
- Internal soft-start: 15ms

Key Design Notes

- The delay time for overload protection is designed to be about 30ms with C107 of 47nF. If faster/slower triggering of OLP is required, C107 can be changed to a smaller/larger value (eg. 100nF for 60ms).
- The input voltage of V_{sync} must be higher than -0.3V. By proper voltage sharing by R106 & R107 resistors, the input voltage can be adjusted.
- The SMD-type 100nF capacitor must be placed as close as possible to V_{CC} pin to avoid malfunction by abrupt pulsating noises and to improved surge immunity.

Schematic

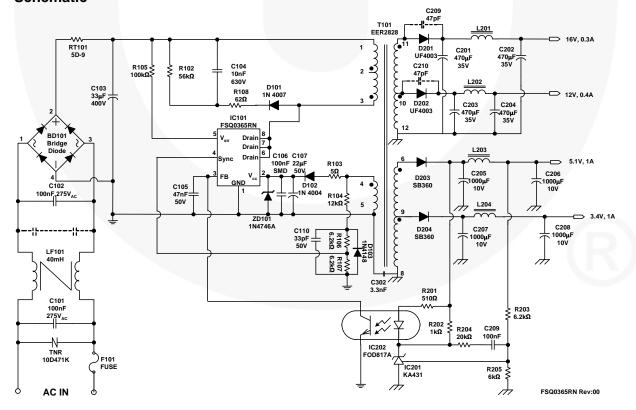


Figure 29. Demo Circuit of FSQ0365RN

Transformer

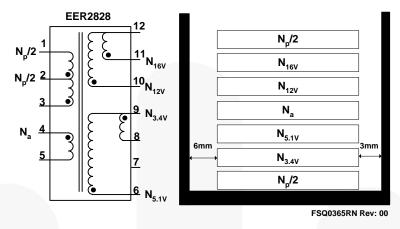


Figure 30. Transformer Schematic Diagram of FSQ0365RN

Table 1. Winding Specification

No.	Pin (s→f)	Wire	Turns	Winding Method
N _p /2	3→2	0.25 [¢] x 1	50	Center Solenoid Winding
Insulation: P	olyester Tape t = 0.050r	nm, 2-Layer		
N _{3.4V}	9→8	0.33 ^{\phi} x 2	4	Center Solenoid Winding
Insulation: P	olyester Tape t = 0.050r	nm, 2-Layer		
N _{5V}	6→9	0.33 [⋄] x 1	2	Center Solenoid Winding
Insulation: P	olyester Tape t = 0.050r	nm, 2-Layer		
N _a	4→5	0.25 ^{\phi} x 1	16	Center Solenoid Winding
Insulation: P	olyester Tape t = 0.050r	nm, 2-Layer		
N _{12V}	10→12	0.33 [¢] x 3	14	Center Solenoid Winding
Insulation: P	olyester Tape t = 0.050r	nm, 3-Layer	•	
N _{16V}	11→12	0.33 ^{\phi} x 3	18	Center Solenoid Winding
Insulation: P	olyester Tape t = 0.050r	nm, 2-Layer		
N _p /2	2→1	0.25 ^{\phi} x 1	50	Center Solenoid Winding
Insulation: P	olyester Tape t = 0.050r	nm, 2-Layer		

Table 2. Electrical Characteristics

	Pin	Specification	Remarks
Inductance	1 - 3	1.4mH ± 10%	100kHz, 1V
Leakage	1 - 3	25µH Maximum	Short All Other Pins

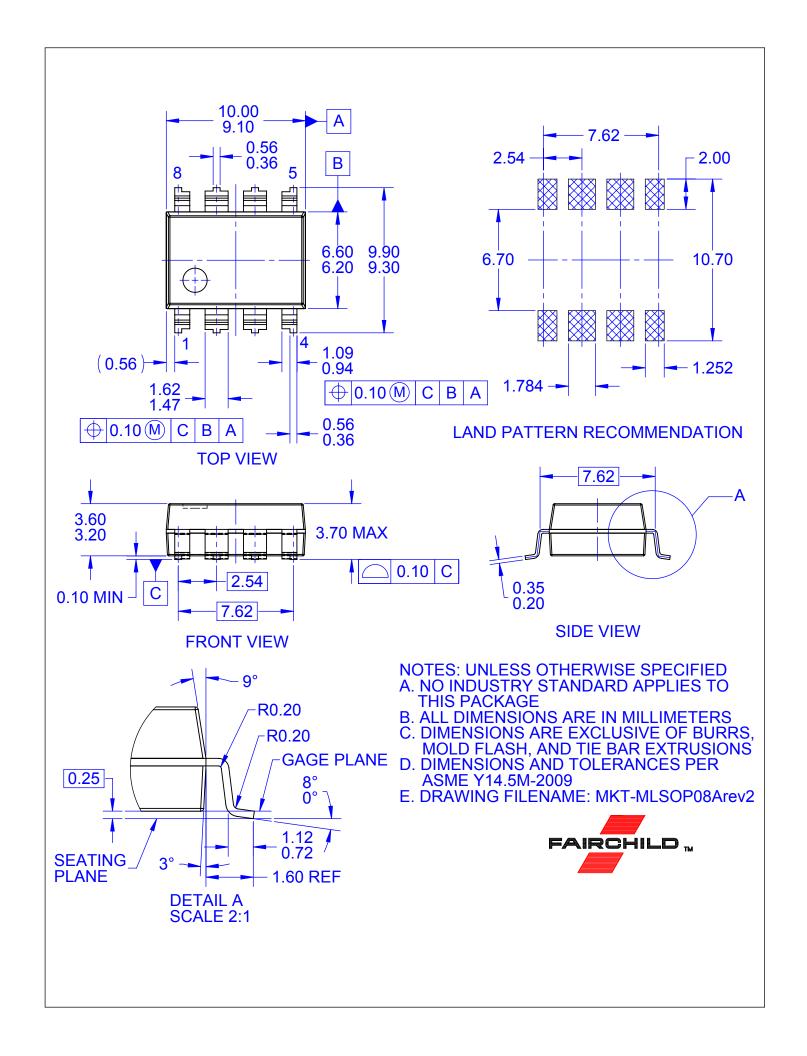
Core & Bobbin

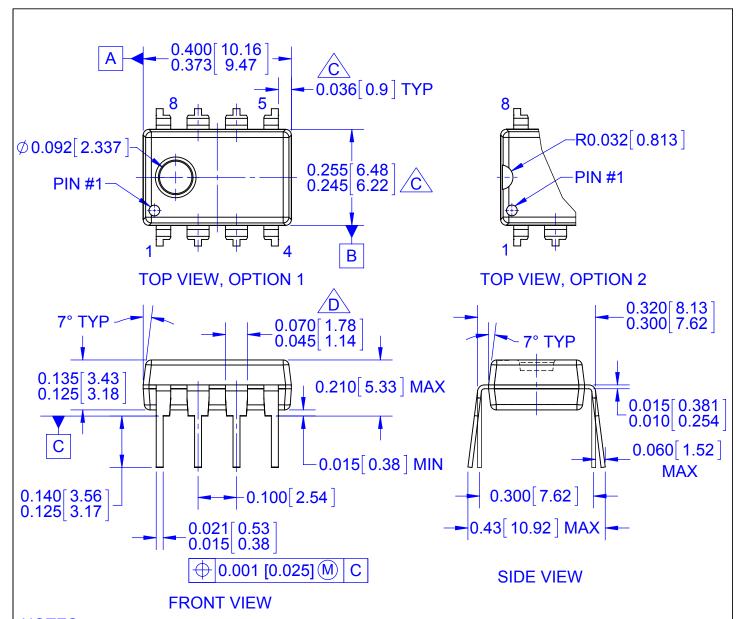
Core: EER2828 (Ae=86.66mm²)

■ Bobbin: EER2828

Table 3. Demo Board Part List

Part	Value	Note	Part	Value	Note
	Resi	stor		Induc	tor
R102	56k	1W	L201	10μH	
R103	5	1/2W	L202	10μH	
R104	12k	1/4W	L203	4.9µH	
R105	100k	1/4W	L204	4.9µH	
R106	6.2k	1/4W		Diod	e
R107	6.2k	1/4W	D101	IN4007	
R108	62	1W	D102	IN4004	
R201	510	1/4W	ZD101	1N4746A	
R202	1k	1/4W	D103	1N4148	
R203	6.2k	1/4W	D201	UF4003	
R204	20k	1/4W	D202	UF4003	
R205	6k	1/4W	D203	SB360	
	Сара	citor	D204 SB360		
C101	100nF/275V _{AC}	Box Capacitor			
C102	100nF/275V _{AC}	Box Capacitor		IC	
C103	33µF/400V	Electrolytic Capacitor	IC101	FSQ0365RN	FPS™
C104	10nF/630V	Film Capacitor	IC201	KA431 (TL431)	Voltage reference
C105	47nF/50V	Mono Capacitor	IC202	FOD817A	Opto-coupler
C106	100nF/50V	SMD (1206)		Fuse	е
C107	22μF/50V	Electrolytic Capacitor	Fuse	2A/250V	
C110	33pF/50V	Ceramic Capacitor		NTC	;
C201	470µF/35V	Electrolytic Capacitor	RT101	5D-9	
C202	470µF/35V	Electrolytic Capacitor		Bridge D	Diode
C203	470µF/35V	Electrolytic Capacitor	BD101	2KBP06M2N257	Bridge Diode
C204	470µF/35V	Electrolytic Capacitor		Line Fi	lter
C205	1000μF/10V	Electrolytic Capacitor	LF101	40mH	
C206	1000μF/10V	Electrolytic Capacitor		Transfo	rmer
C207	1000μF/10V	Electrolytic Capacitor	T101		
C208	1000μF/10V	Electrolytic Capacitor		Varist	tor
C209	100nF /50V	Ceramic Capacitor	TNR	10D471K	





NOTES:

CONFORMS TO JEDEC MS-001, VARIATION BA

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